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N-Channel 200 V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)		
200	0.180 at V _{GS} = 10 V	18		
	0.255 at V _{GS} = 4.5 V	10		

FEATURES



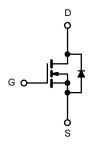


• 175 °C Junction Temperature



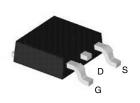
APPLICATIONS

- DC/DC Converters
- DC/AC Inverters
- Motor Drives



N-Channel MOSFET

TO-252 Pin Configuration



Top View

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	200	V	
Gate-Source Voltage	V _{GS}	± 20	7 v	
Continuous Drain Current	T _C = 25 °C		18	
Continuous Drain Current	T _C = 70 °C	I _D	7.5	^
Pulsed Drain Current (t = 300 μs)	I _{DM}	72	A	
Avalanche Current	I _{AS}	25		
Single Avalanche Energy ^a	L = 0.1 mH	E _{AS}	15.7	mJ
Maximum Power Dissipation ^a	T _C = 25 °C	В	85 ^b	W
iviaximum rower bissipation	T _A = 25 °C ^c	P _D	4.1	7 "
Operating Junction and Storage Tempera	T _J , T _{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Limit	Unit		
Junction-to-Ambient (PCB Mount) ^c	R _{thJA}	60	- °C/W		
Junction-to-Case (Drain)	R _{thJC}	1.5			

Notes:

- a. Duty cycle \leq 1 %.
- b. See SOA curve for voltage derating.
- c. When mounted on 1" square PCB (FR-4 material).



Parameter	Symbol	Test Conditions	Min. Typ.		Max.	Unit	
Static	-						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	200			.,	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	1.2		3	V	
Gate-Body Leakage	I _{GSS} V _{DS} = 0 V, V _{GS} = ± 20 V			± 250	nA		
		V _{DS} = 160 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 160 V, V _{GS} = 0 V, T _J = 125 °C			50	μΑ	
		V _{DS} = 160 V, V _{GS} = 0 V, T _J = 175 °C			250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	18			Α	
		V _{GS} = 10 V, I _D = 8 A		0.180	0.220	_	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 6 \text{ A}$	0.255		0.315	Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 6 A	A 20			S	
Dynamic ^b							
Input Capacitance	C _{iss}			2260		pF	
Output Capacitance	C _{oss}	V _{DS} = 160 V, V _{GS} = 0 V, f = 1 MHz		685			
Reverse Transfer Capacitance	C _{rss}			40			
Total Gate Charge ^c	Qg			19.8	30		
Gate-Source Charge ^c	Q _{gs}	V _{DS} = 160 V, V _{GS} = 10 V, I _D = 8 A		3.6		nC	
Gate-Drain Charge ^c	Q _{gd}			4.1			
Gate Resistance	R _g	f = 1 MHz	Hz 2			Ω	
Turn-On Delay Time ^c	t _{d(on)}			8	16		
Rise Time ^c	t _r	$V_{DD} = 160 \text{ V}, R_1 = 9.6 \Omega$		11	20		
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 8 \text{ A, } V_{GEN} = 10 \text{ V, } R_g = 1 \Omega$		18	27	ns	
Fall Time ^c	t _f			5	10		
Drain-Source Body Diode Ratings ar	nd Characteris	stics ^b T _C = 25 °C					
Continuous Current	I _S				18	۸	
Pulsed Current	I _{SM}				72	Α	
Forward Voltage ^a	V _{SD}	$I_F = 5.2 \text{ A}, V_{GS} = 0 \text{ V}$		0.7	1.2	V	
Reverse Recovery Time	t _{rr}			34	51	ns	

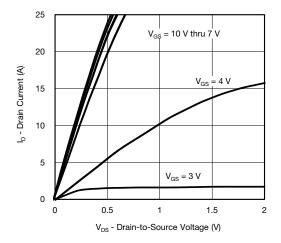
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
 c. Independent of operating temperature.

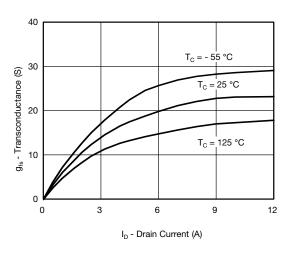
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



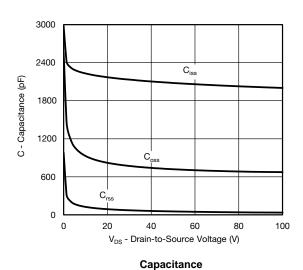
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

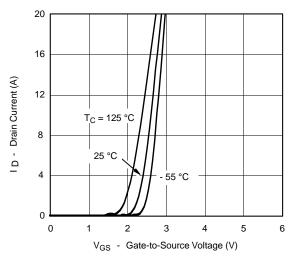


Output Characteristics

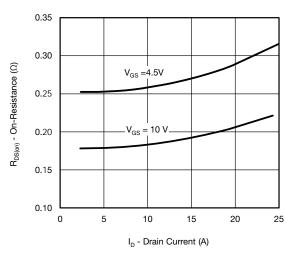


Transconductance

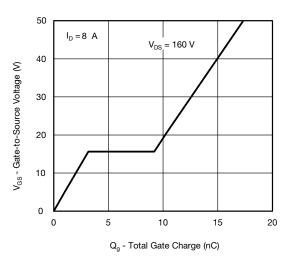




Transfer Characteristics



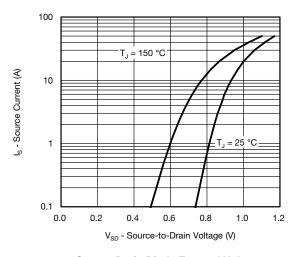
On-Resistance vs. Drain Current



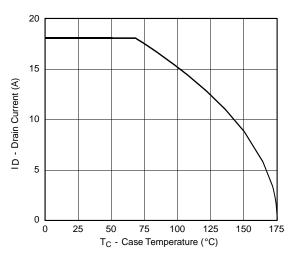
Gate Charge



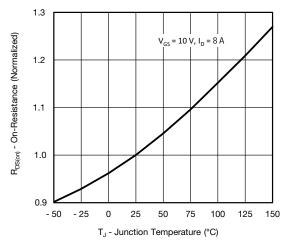
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



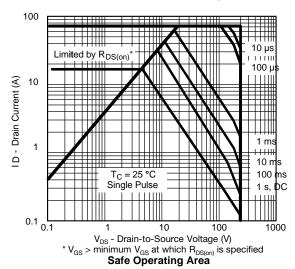
Source-Drain Diode Forward Voltage



Maximum Avalanche Drain Current vs. Case Temperature



On-Resistance vs. Junction Temperature

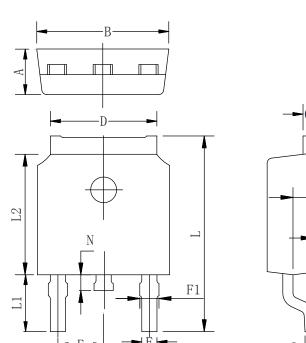


A1

A2

C1





TO-252-2L PACKAGE OUTLINE

COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

Symbol	Min	Тур	Max
A	2.10	2.30	2.50
A1	0.88	1.01	1.16
A2	0.00	0.15	0.28
В	6.40	6.60	6.80
С	0.42	0.50	0.63
C1	0.42	0.50	0.63
D	5.08	5.32	5.65
Е	2.286 TYP		
F	0.63	0.76	0.89
F1	0.64	0.86	1.08
L	9.30	9.90	10.80
L1	2.4	2.8	3.6
L2	5.90	6.10	6.55
N	0.57	0.80	1.05





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